

SN74F112

DUAL NEGATIVE-EDGE-TRIGGERED J-K FLIP-FLOP WITH CLEAR AND PRESET

SDFS048A – D2932, MARCH 1987 – REVISED OCTOBER 1993

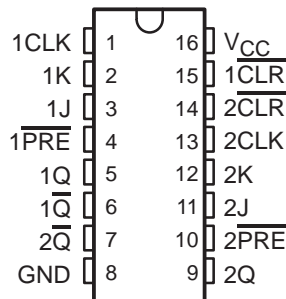
- Package Options Include Plastic Small-Outline Packages and Standard Plastic 300-mil DIPs

description

The SN74F112 contains two independent J-K negative-edge-triggered flip-flops. A low level at the preset (\overline{PRE}) or clear (\overline{CLR}) inputs sets or resets the outputs regardless of the levels of the other inputs. When \overline{PRE} and \overline{CLR} are inactive (high), data at the J and K inputs meeting the setup time requirements is transferred to the outputs on the negative-going edge of the clock pulse. Clock triggering occurs at a voltage level and is not directly related to the rise time of the clock pulse. Following the hold-time interval, data at the J and K inputs may be changed without affecting the levels at the outputs. The SN74F112 can perform as a toggle flip-flop by tying J and K high.

The SN74F112 is characterized for operation from 0°C to 70°C.

D OR N PACKAGE
(TOP VIEW)



FUNCTION TABLE

| INPUTS | | | | | OUTPUTS | |
|------------------|------------------|-----|---|---|----------------|------------------|
| \overline{PRE} | \overline{CLR} | CLK | J | K | Q | \overline{Q} |
| L | H | X | X | X | H | L |
| H | L | X | X | X | L | H |
| L | L | X | X | X | H [†] | H [†] |
| H | H | ↓ | L | L | Q ₀ | \overline{Q}_0 |
| H | H | ↓ | H | L | H | L |
| H | H | ↓ | L | H | L | H |
| H | H | ↓ | H | H | Toggle | |
| H | H | H | X | X | Q ₀ | \overline{Q}_0 |

[†] The output levels in this configuration are not guaranteed to meet the minimum levels for V_{OH} . Furthermore, this configuration is nonstable; that is, it will not persist when either \overline{PRE} or \overline{CLR} returns to its inactive (high) level.

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recommended operating conditions

| | | MIN | NOM | MAX | UNIT |
|----------|--------------------------------|-----|-----|-----|------|
| V_{CC} | Supply voltage | 4.5 | 5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | | V |
| V_{IL} | Low-level input voltage | | | 0.8 | V |
| I_{IK} | Input clamp current | | | -18 | mA |
| I_{OH} | High-level output current | | | -1 | mA |
| I_{OL} | Low-level output current | | | 20 | mA |
| T_A | Operating free-air temperature | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP† | MAX | UNIT |
|-------------------|--|----------------------------|-------------------------|-----|------|------|------|
| V_{IK} | | $V_{CC} = 4.5\text{ V}$, | $I_I = -18\text{ mA}$ | | | -1.2 | V |
| V_{OH} | | $V_{CC} = 4.5\text{ V}$, | $I_{OH} = -1\text{ mA}$ | 2.5 | 3.4 | | V |
| | | $V_{CC} = 4.75\text{ V}$, | $I_{OH} = -1\text{ mA}$ | 2.7 | | | |
| V_{OL} | | $V_{CC} = 4.5\text{ V}$, | $I_{OL} = 20\text{ mA}$ | | 0.3 | 0.5 | V |
| I_I | | $V_{CC} = 5.5\text{ V}$, | $V_I = 7\text{ V}$ | | | 0.1 | mA |
| I_{IH} | | $V_{CC} = 5.5\text{ V}$, | $V_I = 2.7\text{ V}$ | | | 20 | μA |
| I_{IL} | J or K | $V_{CC} = 5.5\text{ V}$, | $V_I = 0.5\text{ V}$ | | | -0.6 | mA |
| | $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ | | | | | -3 | |
| | CLK | | | | | -2.4 | |
| I_{OS}^\ddagger | | $V_{CC} = 5.5\text{ V}$, | $V_O = 0$ | -60 | | -150 | mA |
| I_{CC} | | $V_{CC} = 5.5\text{ V}$, | See Note 2 | | 12 | 19 | mA |

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

NOTE 2: I_{CC} is measured with all outputs open, the Q and \overline{Q} outputs alternately high and the clock input grounded at the time of measurement.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| | | $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ | | MIN | MAX | UNIT |
|--------------------|---|--|-----|-----|-----|------|
| | | MIN | MAX | | | |
| f_{clock} | Clock frequency | 0 | 110 | 0 | 100 | MHz |
| t_w | Pulse duration | CLK high or low | 4.5 | 5 | | ns |
| | | $\overline{\text{CLR}}$ or $\overline{\text{PRE}}$ low | 4.5 | 5 | | |
| t_{su} | Setup time, data before CLK↓ | High | 4 | 5 | | ns |
| | | Low | 3 | 3.5 | | |
| t_h | Hold time, data after CLK↓ | High | 0 | 0 | | ns |
| | | Low | 0 | 0 | | |
| t_{su} | Setup time, inactive state, data before CLK↓§ | | | 4 | 5 | ns |

§ Inactive-state state setup time is also referred to as recovery time.



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switching characteristics (see Note 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 5 V, C _L = 50 pF, R _L = 500 Ω, T _A = 25°C | | | V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX† | | UNIT |
|------------------|--|----------------|---|-----|-----|---|-----|------|
| | | | MIN | TYP | MAX | MIN | MAX | |
| f _{max} | | | 110 | 130 | | 100 | | MHz |
| t _{PLH} | CLK | Q or \bar{Q} | 1.2 | 4.6 | 6.5 | 1.2 | 7.5 | ns |
| t _{PHL} | | | 1.2 | 4.6 | 6.5 | 1.2 | 7.5 | |
| t _{PLH} | $\overline{\text{PRE}}$ or $\overline{\text{CLR}}$ | Q or \bar{Q} | 1.2 | 4.1 | 6.5 | 1.2 | 7.5 | ns |
| t _{PHL} | | | 1.2 | 4.1 | 6.5 | 1.2 | 7.5 | |

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTE 3: Load circuits and waveforms are shown in Section 1.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-----------------|--------------------------------------|----------------------|--------------|-------------------------|---------|
| SN74F112D | LIFEBUY | SOIC | D | 16 | 40 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | F112 | |
| SN74F112DR | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | F112 | Samples |
| SN74F112N | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74F112N | Samples |
| SN74F112NE4 | ACTIVE | PDIP | N | 16 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74F112N | Samples |
| SN74F112NSR | ACTIVE | SO | NS | 16 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | 74F112 | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74F112DR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74F112NSR | SO | NS | 16 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74F112DR | SOIC | D | 16 | 2500 | 340.5 | 336.1 | 32.0 |
| SN74F112NSR | SO | NS | 16 | 2000 | 356.0 | 356.0 | 35.0 |

TUBE


*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| SN74F112D | D | SOIC | 16 | 40 | 507 | 8 | 3940 | 4.32 |
| SN74F112N | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74F112N | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74F112NE4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74F112NE4 | N | PDIP | 16 | 25 | 506 | 13.97 | 11230 | 4.32 |

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.



PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

SOP



4220735/A 12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

EXAMPLE BOARD LAYOUT

NS0016A

SOP - 2.00 mm max height

SOP



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NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

NS0016A

SOP - 2.00 mm max height

SOP



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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